

ELECTRONIC PACKAGING FOR MICROSPACECRAFT APPLICATIONS

David Wasler
Jet Propulsion Laboratory
California Institute of Technology
Pasadena, California 91109

ABSTRACT

The intent of this presentation is to give a brief look into the future of electronic packaging for microspacecraft applications. Advancements in electronic packaging technology areas have developed to the point where a system engineer's visions, concepts and requirements for a microspacecraft can now be a reality. These new developments are ideal candidates for microspacecraft applications. These technologies are capable of bringing about major changes in how we design future spacecraft while taking advantage of the benefits due to size, weight, power, performance, reliability and cost. This presentation will also cover some advantages and limitations of surface mount (SMT), multi-chip modules (MCM) and wafer scale integration (WSI), and what is needed to implement these technologies into microspacecraft.